

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Takahisa YAMAHA

Date: May 25, 2001

Serial No.: Not Yet Known

Group Art Unit: --

Filed: Herewith

Examiner: --

For: METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE (As Amended)

 Assistant Commissioner for Patents
 Washington, D.C. 20231
PRELIMINARY AMENDMENT

Sir:

Preliminary to the examination of the above application, please amend the above-entitled patent application as follows.

FEE CALCULATION

Any additional fee required has been calculated as follows:

_____ If checked, "Small Entity" status is claimed.

	NO. CLAIMS AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		EXTRA PRESENT		RATE		ADDIT. FEE
TOTAL	10	MINUS	20	* =	0	X	(\$9 SE or \$18)	\$	0.00
INDEP.	1	MINUS	3	** =	0	X	(\$40 SE or \$80)	\$	0.00
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X	(\$135 SE or \$270)	\$	0.00
* not less than 20 ** not less than 3									TOTAL \$ 0.00

If any additional payment is required, a check which includes the calculated fee of \$ _____ (OFGS Check No. _____) is attached.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

CONTINGENT EXTENSION REQUEST

If this communication is filed after the shortened statutory time period had elapsed and no separate Petition is enclosed, the Commissioner of Patents and Trademarks is petitioned, under

37 C.F.R. §1.136(a), to extend the time for filing a response to the outstanding Office Action by the number of months which will avoid abandonment under 37 C.F.R. §1.135. The fee under 37 C.F.R. § 1.17 should be charged to our Deposit Account No. 15-0700.

AMENDMENTS

 X If checked, amendment(s) to the specification and/or claims are submitted herewith.

1. If checked, an abstract is submitted as the last page of Appendix A.

2. Specification:

Please add section beginning at page 1, line 2 (after the title) pursuant to 37 C.F.R. § 1.121(b)(ii) attached hereto as Appendix A. Entry is respectfully requested.

3. Claims:

Please cancel claims 1-12 without prejudice.

 If checked, the optional complete set of “clean” claims pursuant to 37 C.F.R. § 1.121(c)(3) is attached hereto as Appendix C.

4. Title:

Please amend the title to read: --METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE--.

REMARKS

In view of the foregoing amendments, Applicant respectfully requests favorable consideration and early passage to issue of the present application.

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail Post Office to Addressee (mail label #EL611014165US) in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 25, 2001:

Dorothy Jenkins

Name of Person Mailing Correspondence

Dorothy Jenkins

Signature

May 25, 2001

Date of Signature

SIW:lac

Respectfully submitted,

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APPENDIX A
“Clean” Version of Each Paragraph/Section/Claim
37 C.F.R. § 1.121(b)(ii) and (c)(i)

TITLE:

Replacement title at page 1, line 1:

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE

SPECIFICATION:

New section beginning at page 1, line 2 (after the title):

CROSS REFERENCE TO RELATED APPLICATIONS

This is a divisional of U.S. Patent Application Serial No. 09/407,910, filed September 29, 1999 in the name of Takahisa Yamaha and entitled BONDING PAD STRUCTURE OF SEMICONDUCTOR DEVICE.

00511557.1

APPENDIX B
Version with Markings to Show Changes Made
37 C.F.R. § 1.121(b)(iii) and (c)(ii)

TITLE:

Title at page 1, line 1:

[BONDING PAD STRUCTURE OF] METHOD FOR MANUFACTURING A
SEMICONDUCTOR DEVICE

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